



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-03-01
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STB40N60M2	XLD2*MQ6LB62	A	SHENZHEN B/E	2016-03-01
Amount		UoM	Unit type	ST ECOPACK Grade
1380.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10.2, 9.15, 4.5	2	GULL WING	
Comment	D2PAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	XLD2*MQ6LB2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	23.466	mg	supplier	die	Silicon (Si)	7440-21-3		22.535	mg	960326	16330
				supplier	metallization	Aluminium (Al)	7429-90-5		0.448	mg	19091	325
				supplier	Passivation	Silicon Nitride	12033-89-5		0.106	mg	4517	77
				supplier	Passivation	Silicon Oxide	7631-86-9		0.158	mg	6733	114
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.011	mg	469	8
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.154	mg	6563	112
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.054	mg	2301	39
				supplier	alloy	Copper (Cu)	7440-50-8		777.537	mg	997396	563433
Leadframe	Copper & its alloys	779.567	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.358	mg	459	259
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.654	mg	839	474
				supplier	metallization	Nickel (Ni)	7440-02-0		1.012	mg	1298	733
				supplier	metallization	Phosphorus (P)	12185-10-3		0.006	mg	8	4
				supplier								
Soft solder	Solder	20.608	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	19.681	mg	955017	14262
				supplier	solder	Silver (Ag)	7440-22-4		0.515	mg	24990	373
				supplier	solder	Tin (Sn)	7440-31-5		0.412	mg	19992	299
Bonding wires	Other inorganic materials	1.212	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.211	mg	999340	878
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	660	1
Encapsulation	Other Organic Materials	552.658	mg	supplier	mold compound	Silica, vitreous	60676-86-0		483.576	mg	875000	350417
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-b	EC 413-900-7		22.106	mg	39999	16019
				supplier	mold compound	Epoxy Resin	25068-38-6		16.580	mg	30000	12014
				supplier	mold compound	phenol resin	29690-82-2		27.633	mg	50000	20024
				supplier	mold compound	Carbon black	1333-86-4		2.763	mg	4999	2002
Connections coating	Solder	2.489	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804